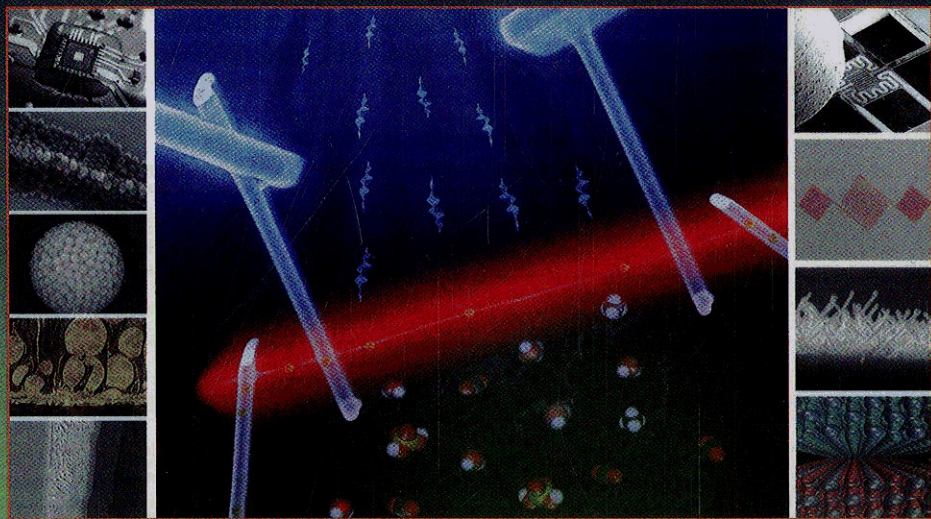


Ceramic Integration and Joining Technologies

From Macro to Nanoscale

Edited by

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